# **Zener Voltage Regulators**

# 200 mW SOD-323 Surface Mount **Tight Tolerance Portfolio**

This series of Zener diodes is packaged in a SOD-323 surface mount package that has a power dissipation of 200 mW. They are designed to provide voltage regulation protection and are especially attractive in situations where space is at a premium. They are well suited for applications such as cellular phones, hand-held portables, and high density PC boards.

#### **Specification Features**

- Standard Zener Breakdown Voltage Range 3.3 V to 36 V
- Steady State Power Rating of 200 mW
- Small Body Outline Dimensions:
  - 0.067" x 0.049" (1.7 mm x 1.25 mm)
- Low Body Height: 0.035" (0.9 mm)
- Package Weight: 4.507 mg/unit
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- Tight Tolerance V<sub>Z</sub>
- AEC-Q101 Qualified and PPAP Capable
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **Mechanical Characteristics:**

**CASE:** Void-free, transfer-molded plastic FINISH: All external surfaces are corrosion resistant MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:

260°C for 10 Seconds

LEADS: Plated with Pb-Sn or Sn only (Pb-Free) **POLARITY:** Cathode indicated by polarity band FLAMMABILITY RATING: UL 94 V-0 **MOUNTING POSITION:** Any



## **ON Semiconductor®**

http://onsemi.com



SOD-323 **CASE 477** STYLE 1



### **MARKING DIAGRAM**



XX = Specific Device Code M = Date Code\*

## = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MM3ZxxxST1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
SZMM3ZxxxST1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
MM3ZxxxST3G	SOD-323 (Pb-Free)	10,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **DEVICE MARKING INFORMATION** See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of

this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) @ T <sub>A</sub> = 25°C Derate above 25°C	PD	200 1.5	mW mW/°C
Thermal Resistance from Junction-to-Ambient	$R_{ hetaJA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 Minimum Pad.

### **ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> =  $25^{\circ}$ C unless otherwise noted,

 $V_F$  = 0.9 V Max. @  $I_F$  = 10 mA for all types)

Symbol	Parameter					
VZ	Reverse Zener Voltage @ I <sub>ZT</sub>					
I <sub>ZT</sub>	Reverse Current					
Z <sub>ZT</sub>	Maximum Zener Impedance @ I <sub>ZT</sub>					
I <sub>ZK</sub>	Reverse Current					
Z <sub>ZK</sub>	Maximum Zener Impedance @ I <sub>ZK</sub>					
I <sub>R</sub>	Reverse Leakage Current @ V <sub>R</sub>					
V <sub>R</sub>	Reverse Voltage					
١ <sub>F</sub>	Forward Current					
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>					
ΘVz	Maximum Temperature Coefficient of VZ					
С	Max. Capacitance $@V_R = 0$ and f = 1 MHz					



Device*	Device Marking	Test Current Izt mA	Zener Voltage VZ		Z <sub>ZK</sub> I <sub>Z</sub> = 0.5	Z <sub>ZT</sub> I <sub>Z</sub> = IZT @ 10%	Max IR @ VR		d <sub>VZ</sub> /dt (mV/k) @ I <sub>ZT1</sub> = 5 mA		C pF Max @
			Min	Max	mA Ω Max	Mod Ω Max	μA	v	Min	Max	V <sub>R</sub> = 0 f = 1 MHz
MM3Z3V0ST1G	T4	5.0	2.90	3.11	1000	100	10	1.0	-3.5	0	450
MM3Z3V3ST1G	T5	5.0	3.32	3.53	1000	95	5.0	1.0	-3.5	0	450
MM3Z3V9ST1G	T7	5.0	3.89	4.16	1000	90	3.0	1.0	-3.5	-2.5	450
MM3Z4V3ST1G	Т8	5.0	4.17	4.43	1000	90	3.0	1.0	-3.5	0	450
MM3Z4V7ST1G	Т9	5.0	4.55	4.75	800	80	3.0	2.0	-3.5	0.2	260
MM3Z5V1ST1G	TA	5.0	4.98	5.2	500	60	2.0	2.0	-2.7	1.2	225
MM3Z5V6ST1G	TC	5.0	5.49	5.73	200	40	1.0	2.0	-2.0	2.5	200
MM3Z6V2ST1G	TE	5.0	6.06	6.33	100	10	3.0	4.0	0.4	3.7	185
MM3Z6V8ST1G	TF	5.0	6.65	6.93	160	15	2.0	4.0	1.2	4.5	155
MM3Z7V5ST1G	TG	5.0	7.28	7.6	160	15	1.0	5.0	2.5	5.3	140
MM3Z8V2ST1G	TH	5.0	8.02	8.36	160	15	0.7	5.0	3.2	6.2	135
MM3Z9V1ST1G	ТК	5.0	8.85	9.23	160	15	0.5	6.0	3.8	7.0	130
MM3Z10VST1G	WB	5.0	9.80	10.20	160	15	0.5	6.0	4.5	8.0	130
MM3Z12VST1G	TN	5.0	11.74	12.24	80	25	0.1	8.0	6.0	10	130
MM3Z13VST1G	TQ	5.0	12.91	13.49	160	30	0.1	8.0	7.0	11	120
MM3Z15VST1G	TP	5.0	14.34	14.98	80	40	0.1	11	8.8	12.7	130
MM3Z16VST1G	TU	5.0	15.85	16.51	80	40	0.05	11.2	10.4	14	105
MM3Z18VST1G	TW	5.0	17.56	18.35	80	45	0.05	12.6	12.4	16	100
MM3Z22VST1G	WP	5.0	21.54	22.47	100	55	0.05	15.4	16.4	20	85
MM3Z24VST1G	WT	5.0	23.72	24.78	120	70	0.05	16.8	18.4	22	80
MM3Z27VST1G	WQ	5.0	26.19	27.53	300	80	0.05	18.9	21.4	25.3	70
MM3Z33VST1G	WR	5.0	32.15	33.79	300	80	0.05	23.2	27.4	33.4	70
MM3Z36VST1G	WU	5.0	35.07	36.87	500	90	0.05	25.2	30.4	37.4	70
MM3Z39VST1G	WN	2.0	38.22	39.78	500	130	0.05	27.3	33.4	41.2	45

### **ELECTRICAL CHARACTERISTICS** (V<sub>F</sub> = 0.9 Max @ I<sub>F</sub> = 10 mA for all types)

\*Include SZ-prefix devices where applicable.

## **TYPICAL CHARACTERISTICS**



#### PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE H





NOTES

1. DIMENSIONING AND TOLERANCING PER ANSI

- Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS. з. LEAD THICKNESS SPECIFIED PER L/F DRAWING
- WITH SOLDER PLATING
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. 5. DIMENSION L IS MEASURED FROM END OF

RADIUS.

	MIL		ERS	INCHES				
DIM	MIN	NOM	MAX	MIN	NOM	MAX		
Α	0.80	0.90	1.00	0.031	0.035	0.040		
A1	0.00	0.05	0.10	0.000	0.002	0.004		
A3	(	).15 REI	F	0.006 REF				
b	0.25	0.32	0.4	0.010	0.012	0.016		
С	0.089	0.12	0.177	0.003	0.005	0.007		
D	1.60	1.70	1.80	0.062	0.066	0.070		
Е	1.15	1.25	1.35	0.045	0.049	0.053		
L	0.08			0.003				
HE	2.30	2.50	2.70	0.090	0.098	0.105		

STYLE 1: PIN 1. CATHODE 2. ANODE

## SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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